

Electronic Patent Application Fee Transmittal				
Application Number:		10594221		
Filing Date:		25-Sep-2006		
Title of Invention:		SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED PRODUCT THEREOF		
First Named Inventor/Applicant Name:		Takashi Sueyoshi		
Filer:		Eric Jensen/Deidre Washington		
Attorney Docket Number:		8007-1116		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1819